

FEATURES

- Dual Device Module
- Electrically Isolated Package
- Pressure Contact Construction
- International Standard Footprint
- Alumina (Non Toxic) Isolation Medium
- Integral Water Cooled Heatsink

APPLICATIONS

- Welding

VOLTAGE RATINGS

Type Number	Repetitive Peak Voltages V_{DRM} V_{RRM} V	Conditions
MP03TT1250-18	1800	$T_{vj} = 0^{\circ} \text{ to } 125^{\circ}\text{C}$, $I_{DRM} = I_{RRM} = 30\text{mA}$ $V_{DSM} = V_{RSM} =$ $V_{DRM} = V_{RRM} + 100\text{V}$ respectively
MP03TT1250-17	1700	
MP03TT1250-16	1600	
MP03TT1250-15	1500	

Lower voltage grades available

ORDERING INFORMATION

Order As:

MP03TT1250-XX W1	With 1/4 BSP connection
MP03TT1250-XX W2	1/4 – 18 NPT connection
MP03TT1250-XX W3	1/4 – 18 NPT connection
MP03TT1250-XX W3A	1/4 – 18 NPT water connection thread
MP03TT1250-XX W4	With 1/4 BSP connection

XX shown in the part number about represents $V_{DRM}/100$ selection required, e.g. MP03TT1250-16-W3

Note: When ordering, please use the whole part number.

Auxiliary gate and cathode leads can be ordered separately.

KEY PARAMETERS

V_{DRM}	1800V
$I_{LINE(cont.)}$	798A
$I_{LINE(20cy./50\%)}$	1258A
$I_{TSM(per arm)}$	8100A
V_{isol}	3000V

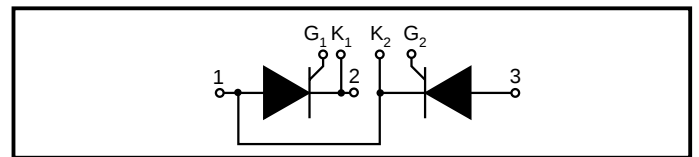


Fig. 1 Circuit diagram

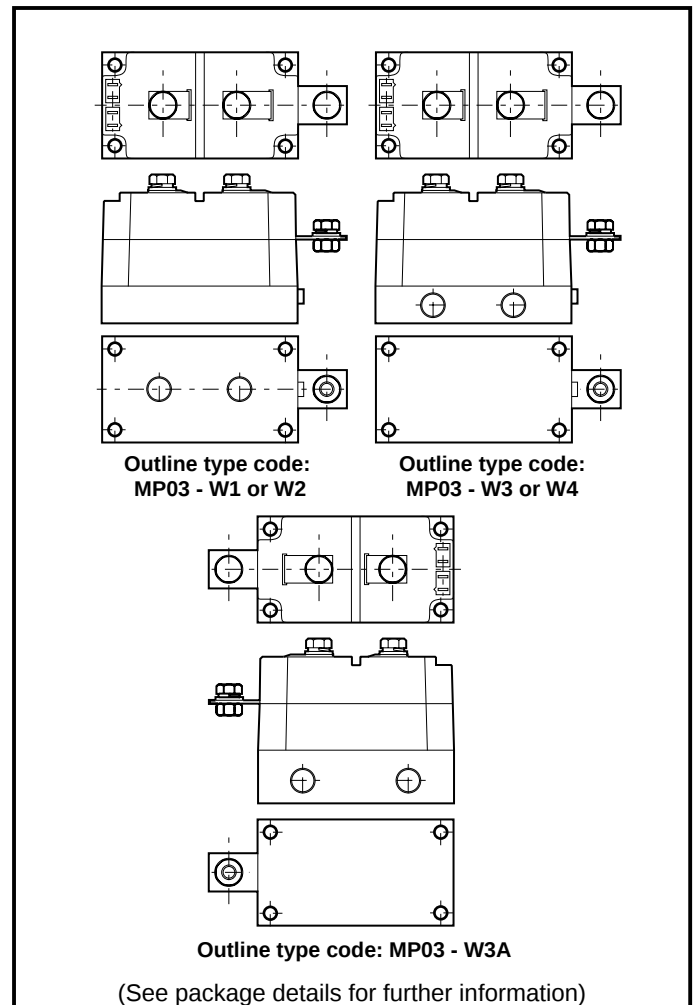


Fig. 2 Electrical connections - (not to scale)

ABSOLUTE MAXIMUM CURRENT RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

Symbol	Parameter	Test Conditions		Max.	Units
I_{LINE}	Max. controllable RMS line current - single phase	Continuous 50/60Hz 4.5 Ltr/min	$T_{water (in)} = 25^{\circ}C$	798	A
			$T_{water (in)} = 40^{\circ}C$	703	A
		20 cycles, 50% duty cycle 4.5 Ltr/min	$T_{water (in)} = 25^{\circ}C$	1410	A
			$T_{water (in)} = 40^{\circ}C$	1258	A
I_{TSM}	Surge (non-repetitive) on-current	10ms half sine, $T_j = 125^{\circ}C$		8.1	kA
I^2t	I^2t for fusing	$V_R = 0$		0.33×10^6	A^2s
I_{TSM}	Surge (non-repetitive) on-current	10ms half sine, $T_j = 125^{\circ}C$		6.5	kA
I^2t	I^2t for fusing	$V_R = 50\% V_{DRM}$		0.21×10^6	A^2s
V_{isol}	Isolation voltage	Commoned terminals to base plate. AC RMS, 1 min, 50Hz		3000	V

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
$R_{th(j-w)}$	Thermal resistance - junction to water (per thyristor)	dc, 4.5 Ltr/min	-	0.175	$^{\circ}C/kW$
		Half wave, 4.5 Ltr/min	-	0.185	$^{\circ}C/kW$
		3 Phase, 4.5 Ltr/min	-	0.195	$^{\circ}C/kW$
T_{vj}	Virtual junction temperature	Reverse (blocking)	-	125	$^{\circ}C$
T_{stg}	Storage temperature range	-	-40	125	$^{\circ}C$
-	Screw torque	Mounting - M6	5(44)	-	Nm (lb.ins)
		Electrical connections - M4	8(70)	9(80)	Nm (lb.ins)
-	Weight (nominal)	-	-	Refer to drawing	g

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
I_{RRM}/I_{DRM}	Peak reverse and off-state current	At V_{RRM}/V_{DRM} , $T_j = 125^\circ\text{C}$	-	30	mA
dV/dt	Linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 125^\circ\text{C}$	-	1000	V/ μs
dI/dt	Rate of rise of on-state current	From 67% V_{DRM} to 500A, gate source 10V, 5 Ω $t_r = 0.5\mu\text{s}$, $T_j = 125^\circ\text{C}$	-	500	A/ μs
$V_{T(TO)}$	Threshold voltage	At $T_{vj} = 125^\circ\text{C}$	-	0.93	V
r_T	On-state slope resistance	At $T_{vj} = 125^\circ\text{C}$	-	0.67	m Ω

Note: The data given in this datasheet with regard to forward voltage drop is for calculation of the power dissipation in the semiconductor elements only. Forward voltage drops measured at the power terminals of the module will be in excess of these figures due to the impedance of the busbar from the terminal to the semiconductor.

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5\text{V}$, $T_{case} = 25^\circ\text{C}$	3	V
I_{GT}	Gate trigger current	$V_{DRM} = 5\text{V}$, $T_{case} = 25^\circ\text{C}$	150	mA
V_{GD}	Gate non-trigger voltage	At V_{DRM} $T_{case} = 125^\circ\text{C}$	0.25	V
V_{FGM}	Peak forward gate voltage	Anode positive with respect to cathode	30	V
V_{FGN}	Peak forward gate voltage	Anode negative with respect to cathode	0.25	V
V_{RGM}	Peak reverse gate voltage	-	5	V
I_{FGM}	Peak forward gate current	Anode positive with respect to cathode	10	A
P_{GM}	Peak gate power	See table fig. 5	100	W
$P_{G(AV)}$	Mean gate power	-	5	W

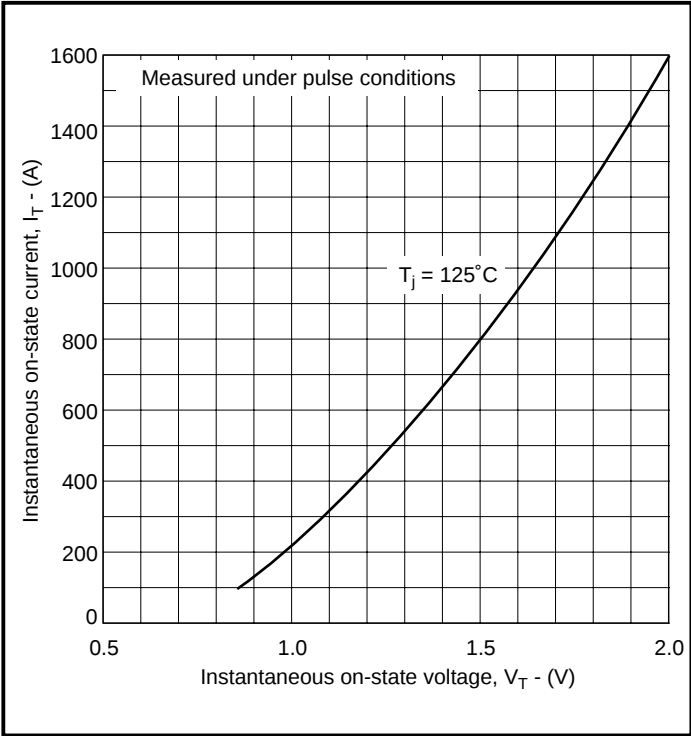


Fig. 3 Maximum (limit) on-state characteristics

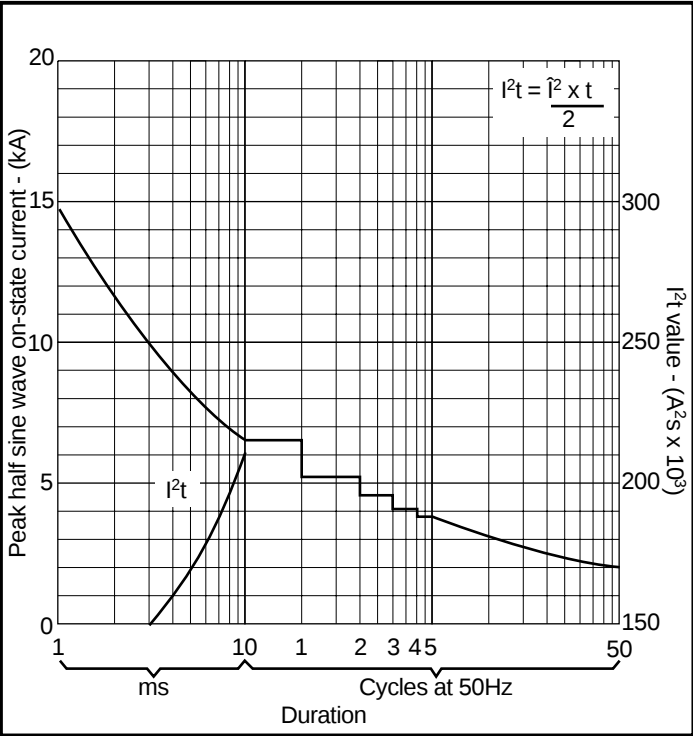


Fig. 4 Surge (non-repetitive) on-state current vs time (with 50% V_{RSM} at $T_{\text{case}} = 125^\circ\text{C}$)

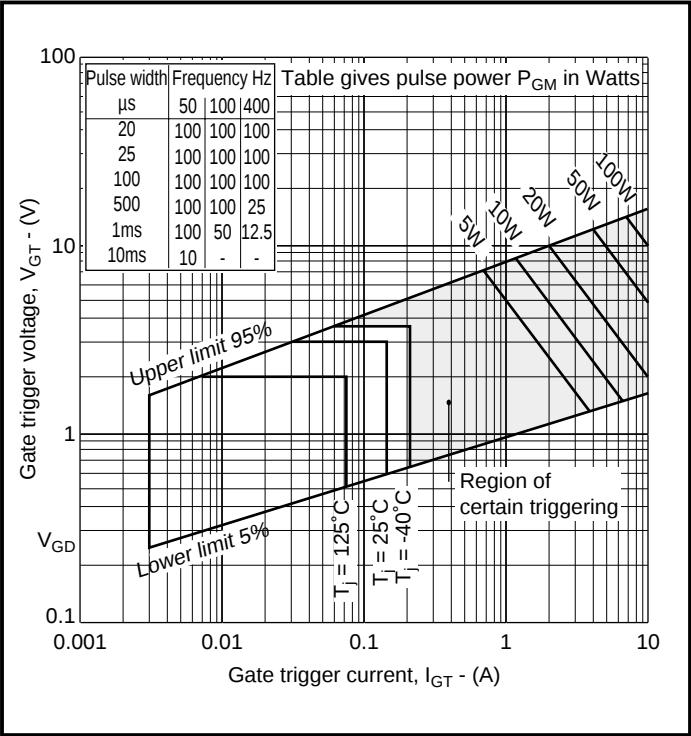


Fig. 5 Gate characteristics

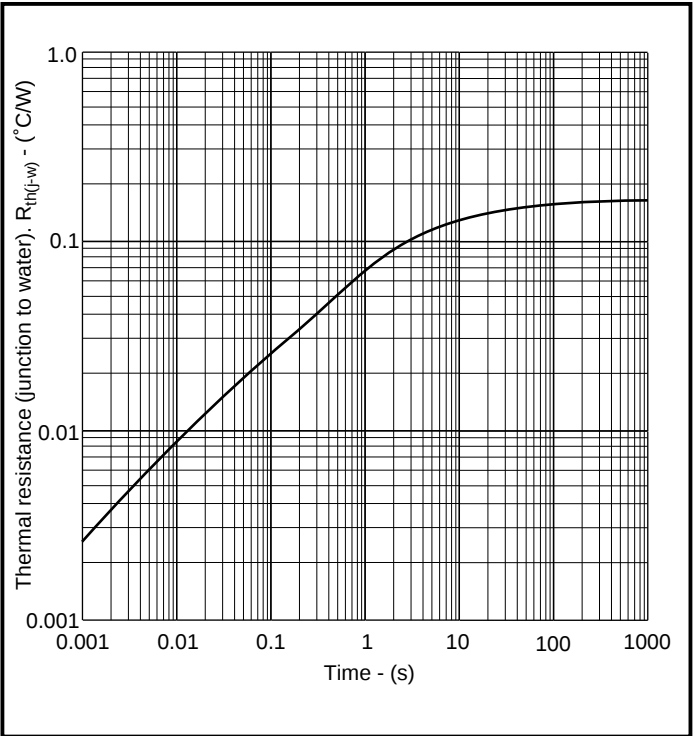
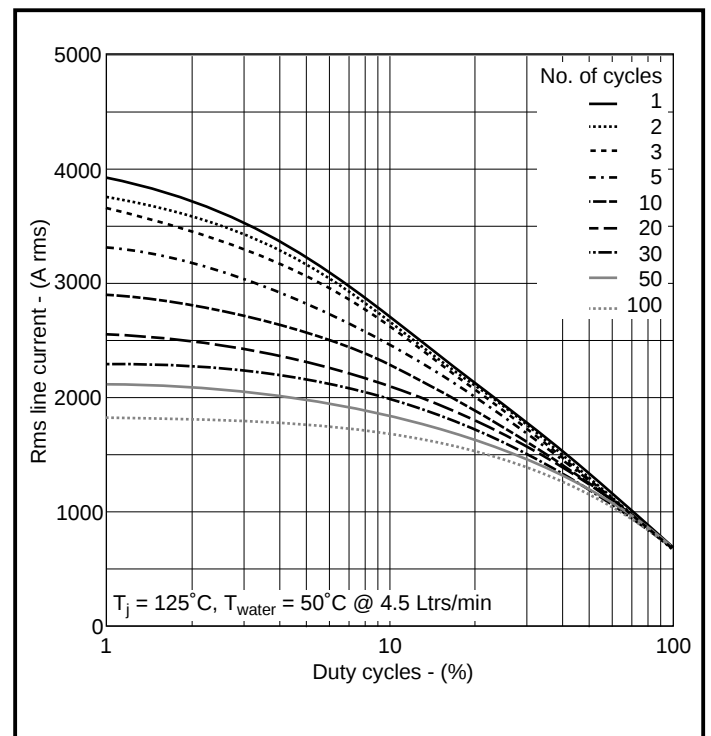
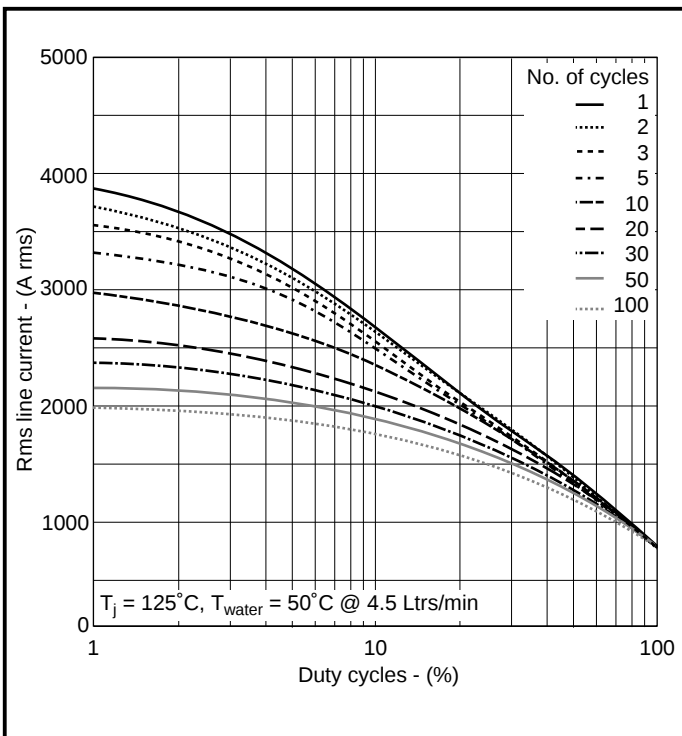
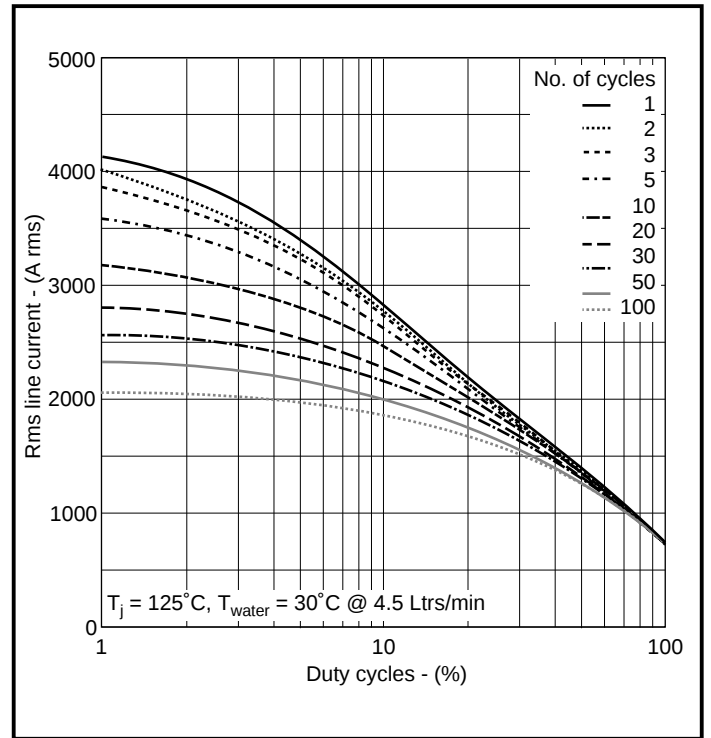
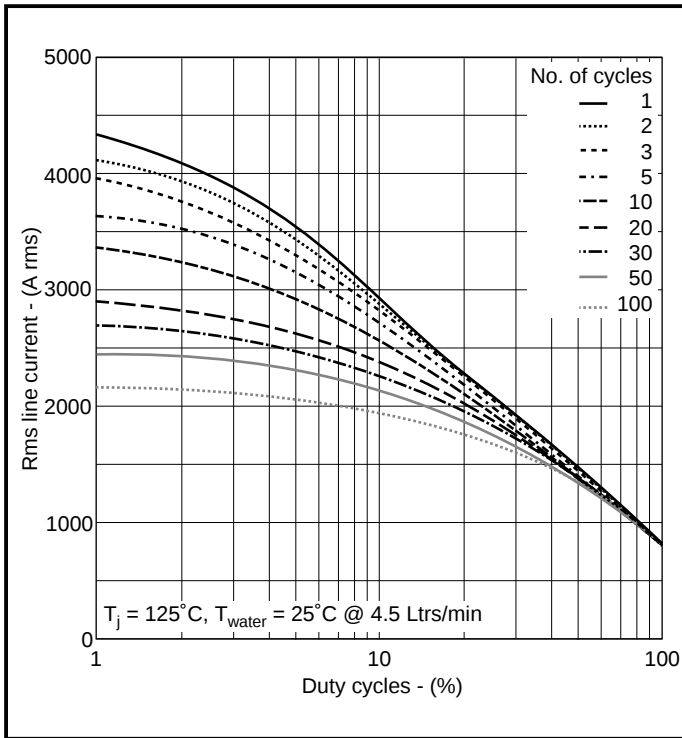
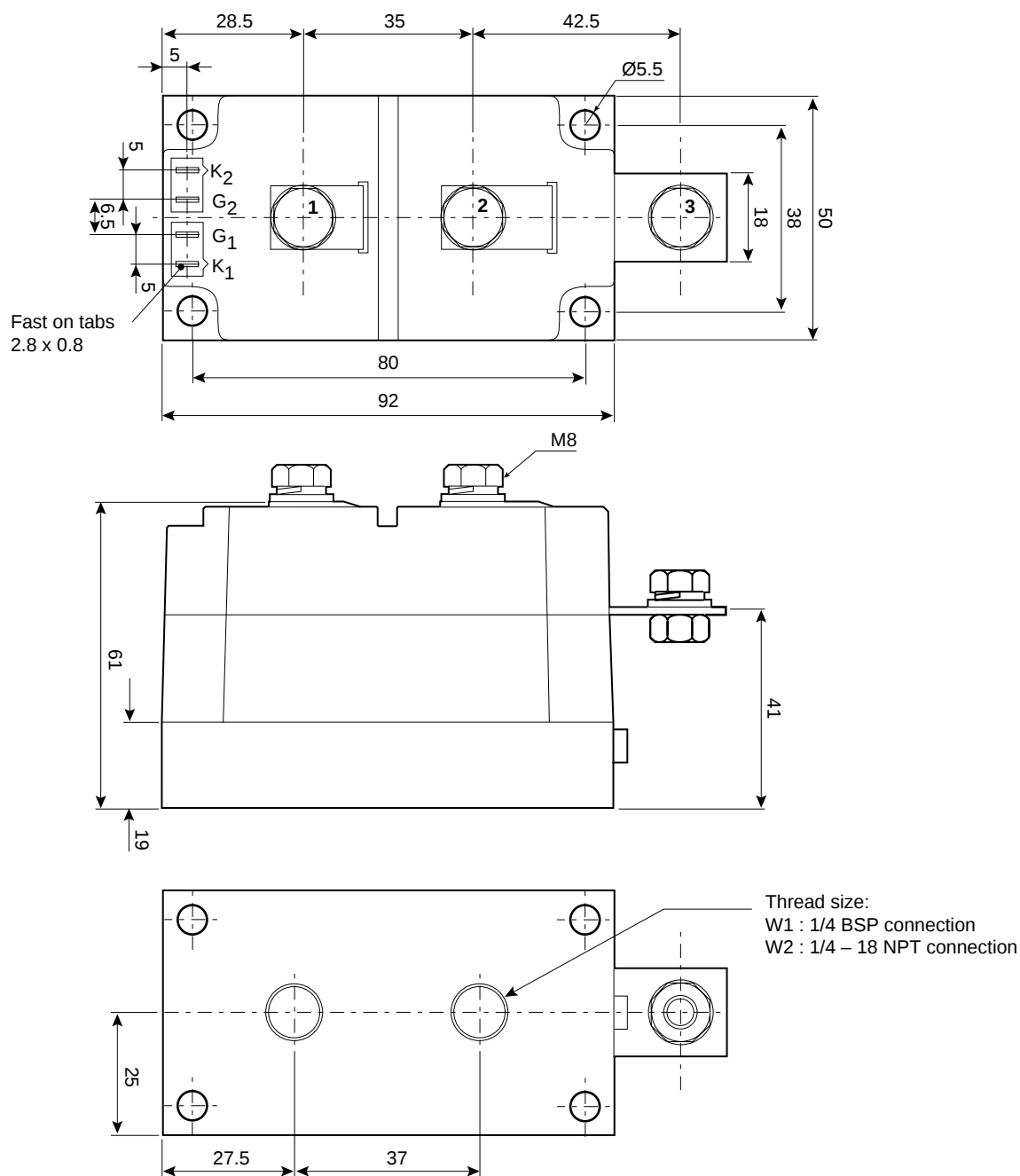


Fig. 6 Transient thermal impedance - dc



PACKAGE DETAILS

For further package information, please visit our website or contact your nearest Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



Recommended fixings for mounting: M5 socket head cap screws

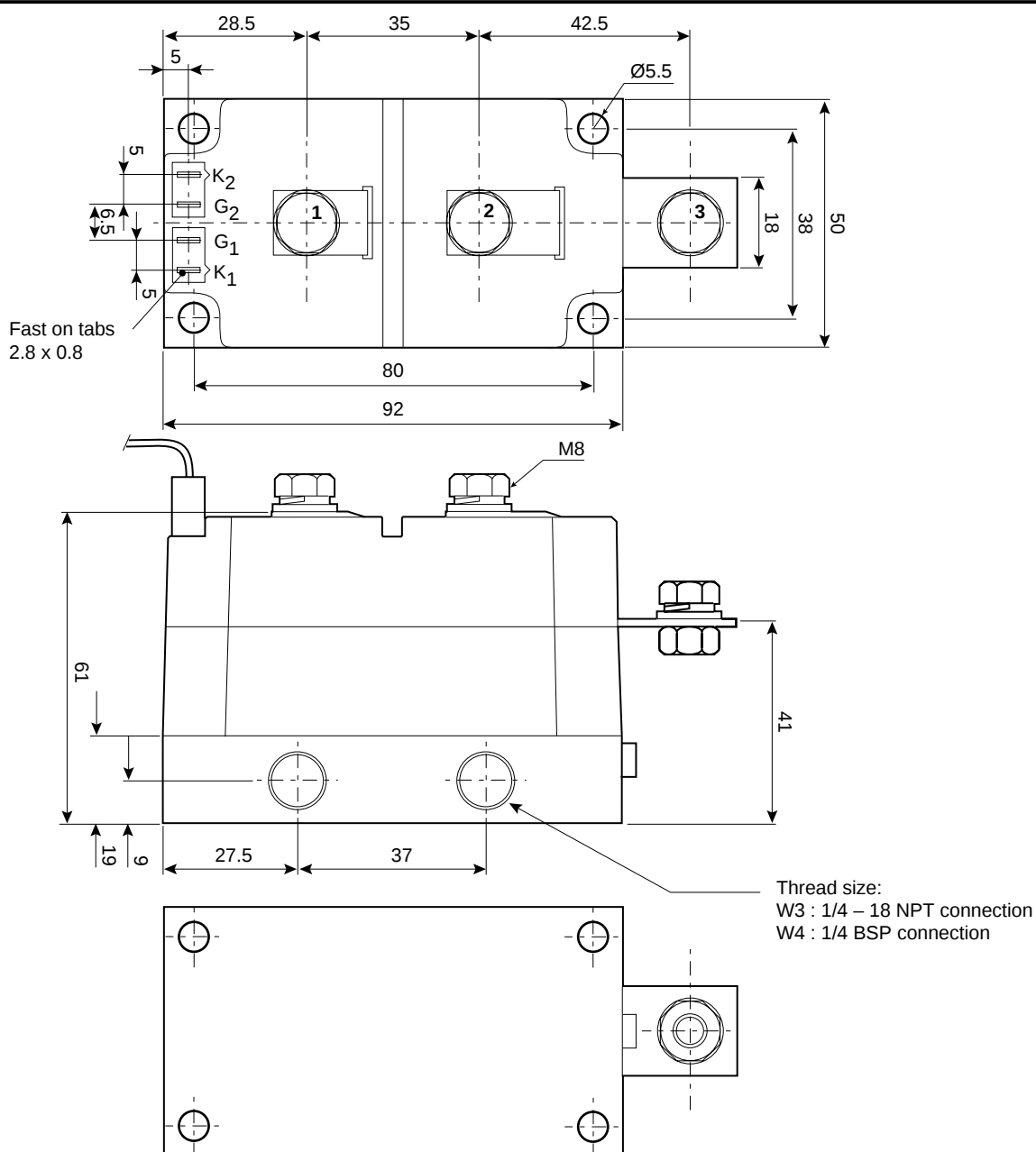
Nominal weight: 1100g

Auxiliary gate/cathode leads not supplied as standard, but maybe purchased separately.

Module outline type code: MP03-W1 and W2

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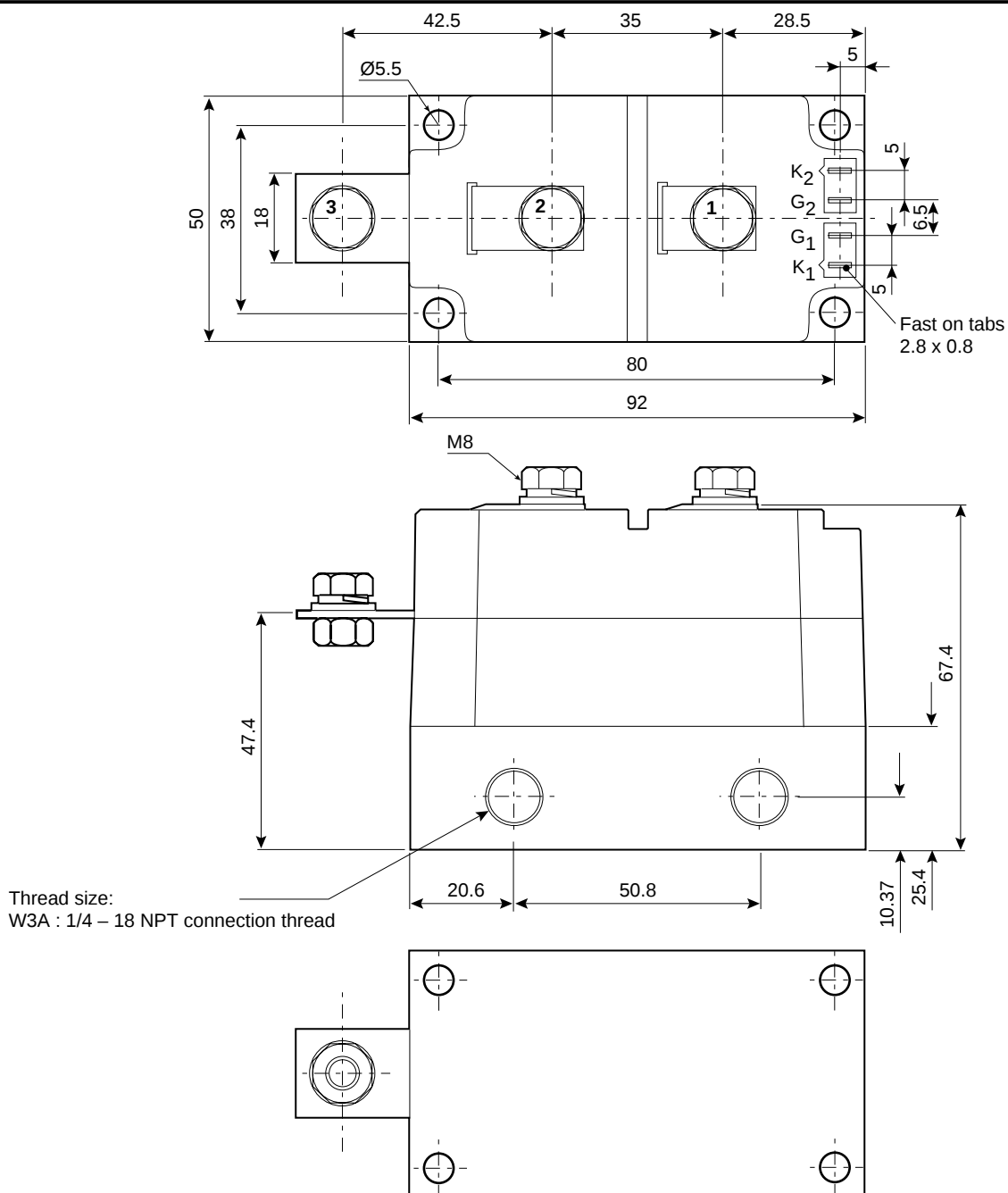


Recommended fixings for mounting: M5 socket head cap screws
Nominal weight: 1100g
Auxiliary gate/cathode leads not supplied as standard, but maybe purchased separately.

Module outline type code: MP03-W3 and W4

PACKAGE DETAILS

For further package information, please visit our website or contact your nearest Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



Thread size:
W3A : 1/4 – 18 NPT connection thread

Recommended fixings for mounting: M5 socket head cap screws

Nominal weight: 1300g

Auxiliary gate/cathode leads not supplied as standard, but maybe purchased separately.

Module outline type code: MP03-W3A

POWER ASSEMBLY CAPABILITY

The Power Assembly group provides support for those customers requiring more than the basic semiconductor switch. Using CAD design tools the group has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of Dynex semiconductors.

An extensive range of air and liquid cooled assemblies is available covering the range of circuit designs in general use today.

HEATSINKS

The Power Assembly group has a proprietary range of extruded aluminium heatsinks. These were designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or customer service office.



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Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

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